



## TCT and CCE measurements for 9 MeV and 24 GeV/c irradiated n-type MCz-Si pad detectors

J. Härkönen<sup>1)</sup>, E. Tuovinen<sup>1)</sup>, S. Czellar<sup>1)</sup>, I. Kassamakov<sup>1)</sup>, P. Luukka<sup>1)</sup>,  
E. Tuominen<sup>1)</sup>, S. Väyrynen<sup>2)</sup> and J. Räisänen<sup>2)</sup>

<sup>1)</sup>*Helsinki Institute of Physics, CMS Tracker Project.*

<sup>2)</sup>*Accelerator Laboratory, University of Helsinki*

<http://www.hip.fi/research/cms/tracker/php/home.php>



## Outline

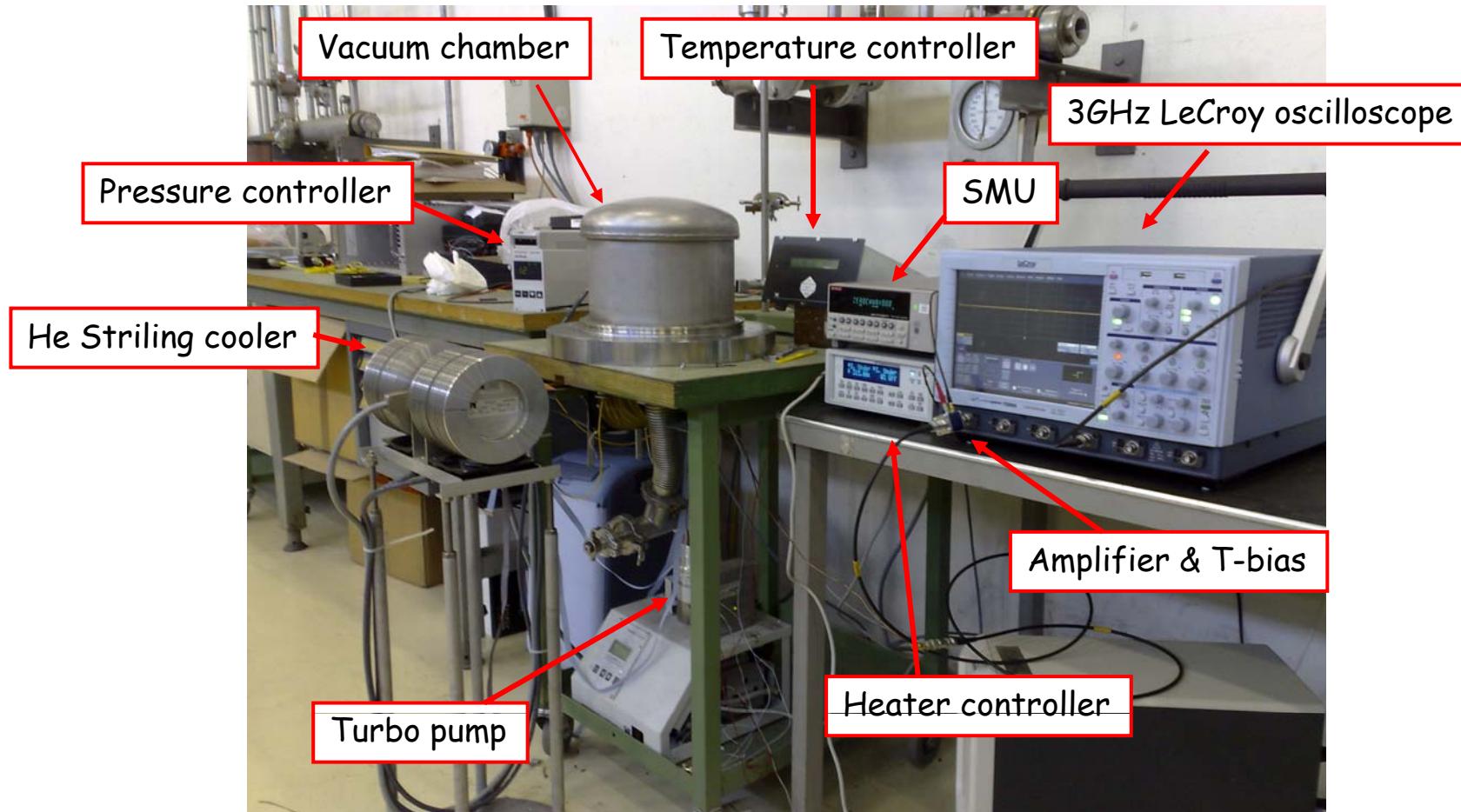
- Samples and irradiations
- Measurement setup
- Red laser measurements (TCT)
- IR laser measurements (CCE)
- Summary
- References

Esa Tuovinen loading MCz-Si wafers into oxidation furnace at the Microelectronics Center of Helsinki University of Technoly, Finland.



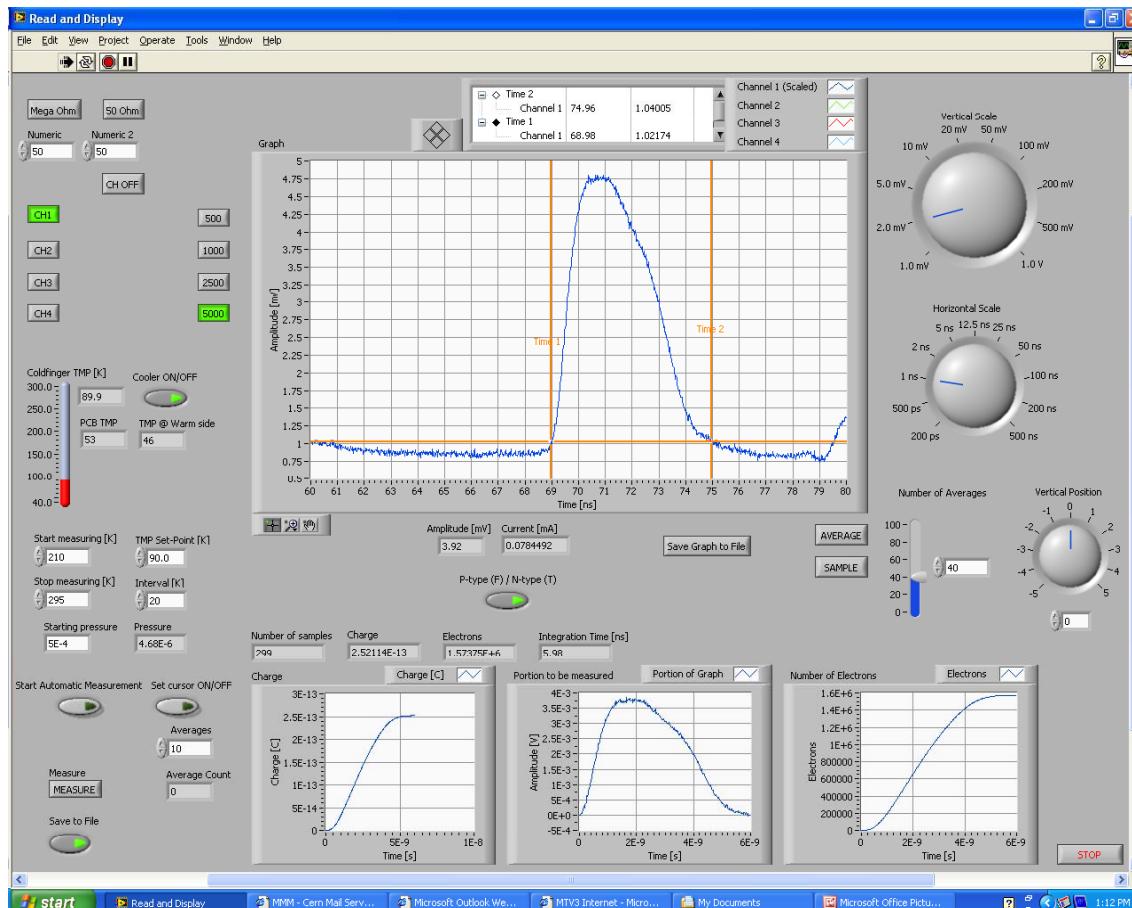


## Cryogenic Transient Current Technique (C-TCT)





# Properties of Setup

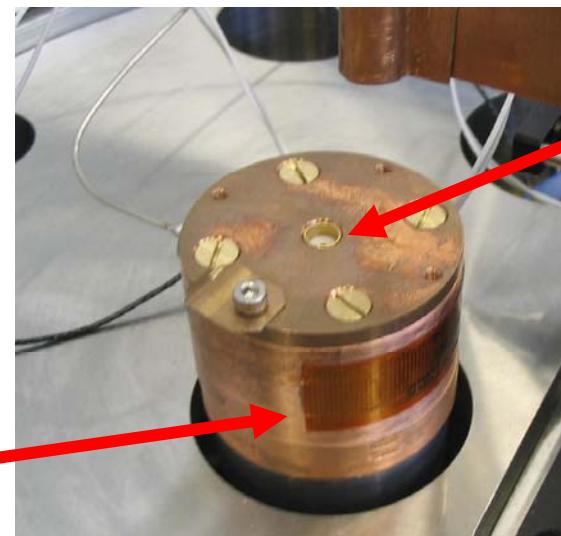
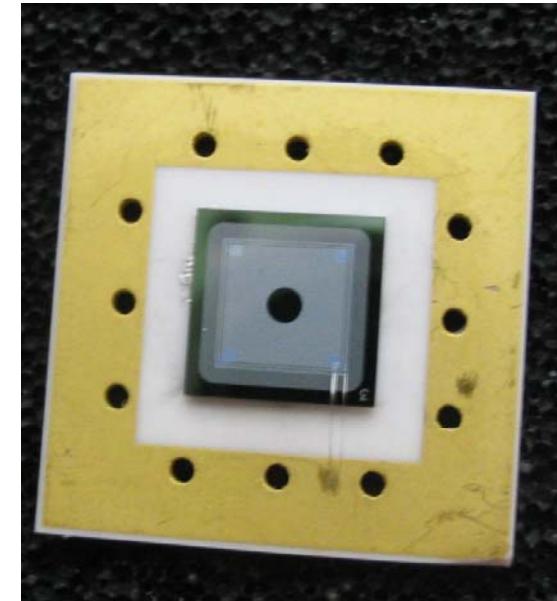
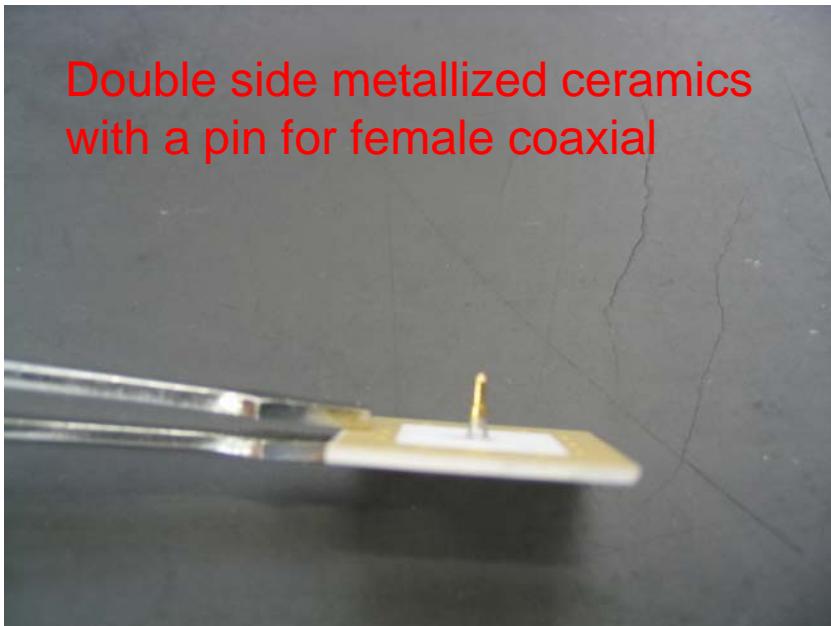


1. IR (1060nm) and RED (670nm) lasers.
2. Front side illumination only.
3. Temperature min 40K.
4. Fully computer control (system and DAQ).
5. Bias up to 600V.
6. High gain preamplifier for CCE ( $g \approx 600$ ) and TCT ( $g \approx 35$ ). Optimized for low injection level (CCE) and high bandwidth (TCT)



## Samples adjustment

- Ceramic sample holders

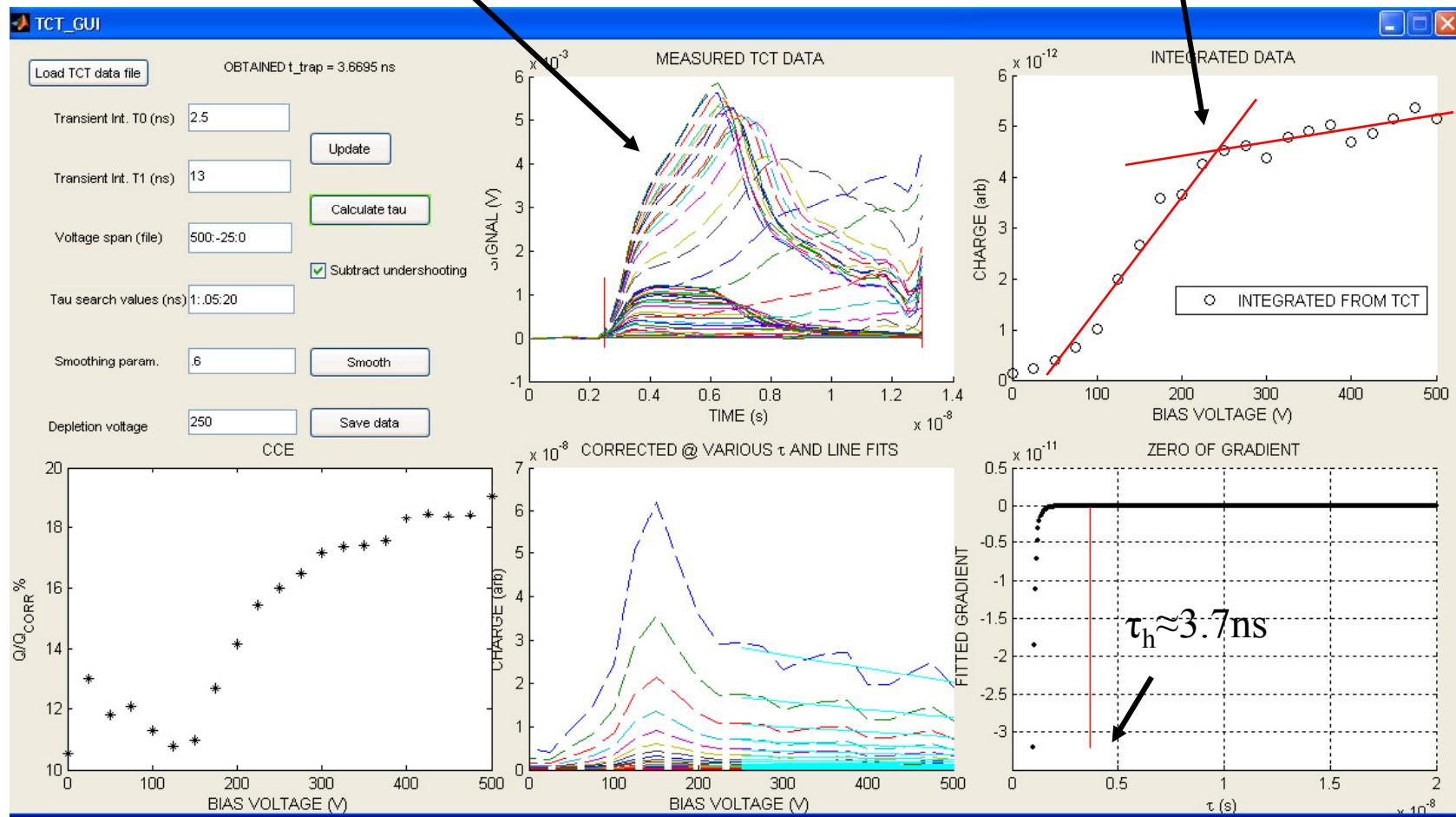


Heating resistor provides faster temperature ramping



# C-TCT data analysis

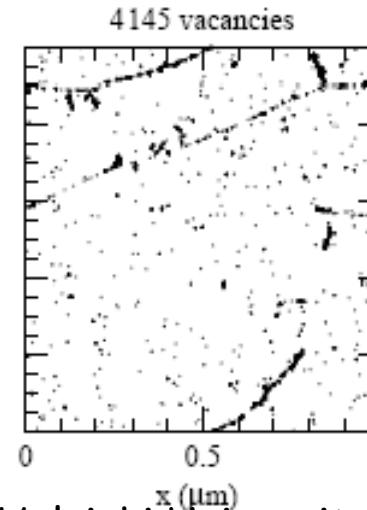
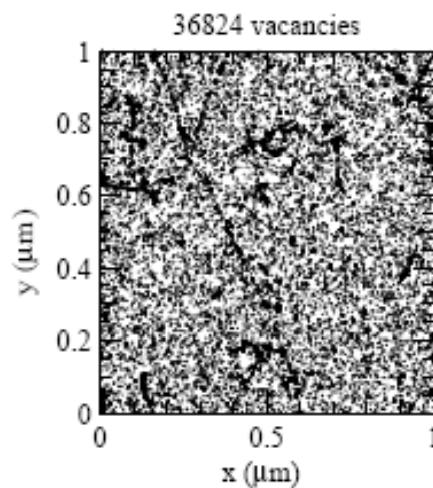
## Trapping corrected transient





## Samples and irradiations

- 9 MeV proton irradiation at University of Helsinki Accelerator laboratory
- Fluencies up to  $3 \times 10^{15} \text{ n}_{\text{eq}}/\text{cm}^2$
- Hardness factor  $\sim 5$
- 24 GeV proton irradiation at CERN Irrad1-facility
- Fluencies up to  $1.6 \times 10^{16} \text{ p}/\text{cm}^2$
- Hardness factor  $\sim 0.6$



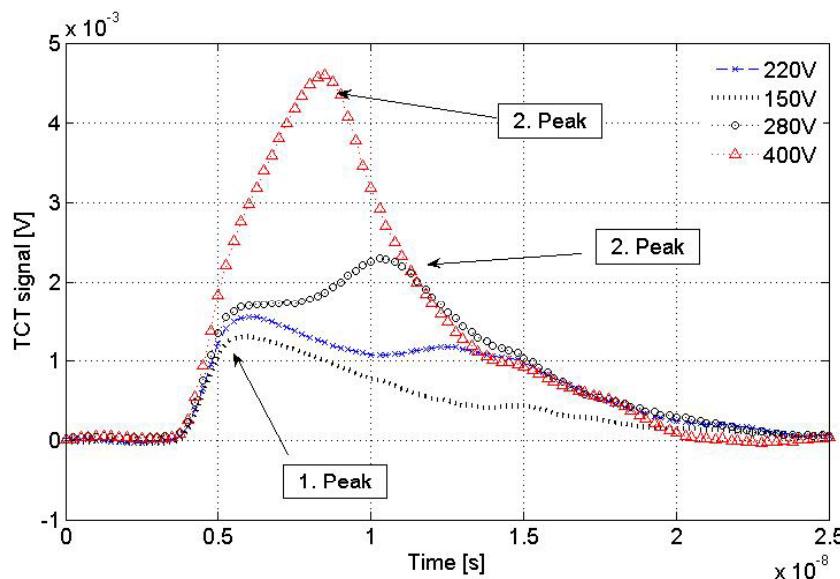
Mika Huhtinen, NIMA 491 (2002)

- Samples processed at MINFAB facility of Helsinki University of Technology on Okmetic MCz-Si wafers.
- "Standard" RD50 diode process and design

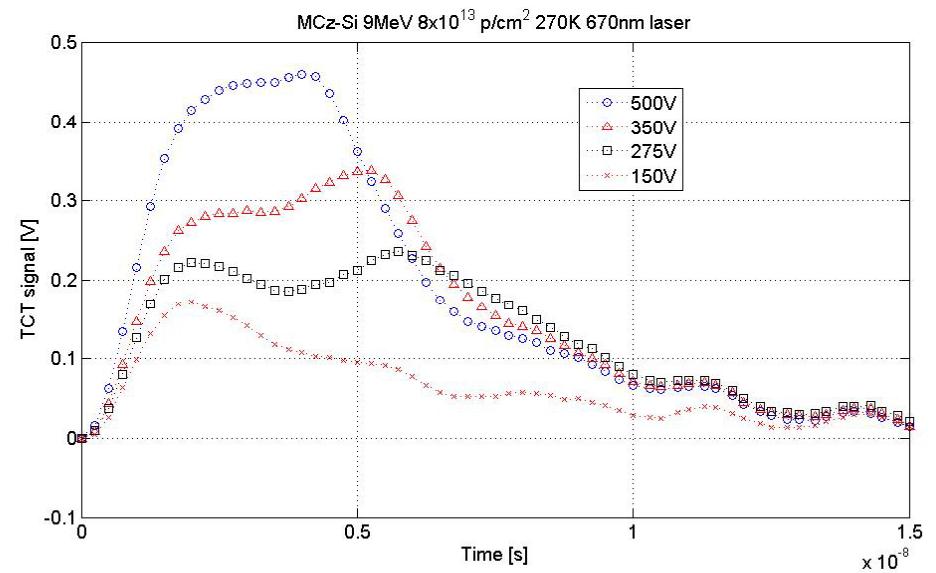


## TCT red laser results low energy protons 1

MCz-Si  $7 \times 10^{14}$  n<sub>eq</sub>/cm<sup>2</sup> by 50 MeV protons



MCz-Si  $4 \times 10^{14}$  n<sub>eq</sub>/cm<sup>2</sup> by 9 MeV protons

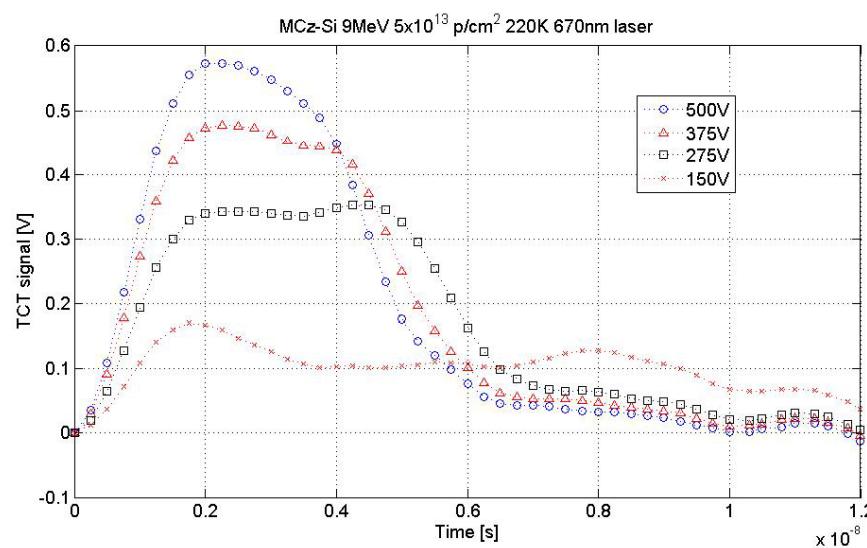


- No trapping correction
- DP arises in 50MeV and 9MeV both

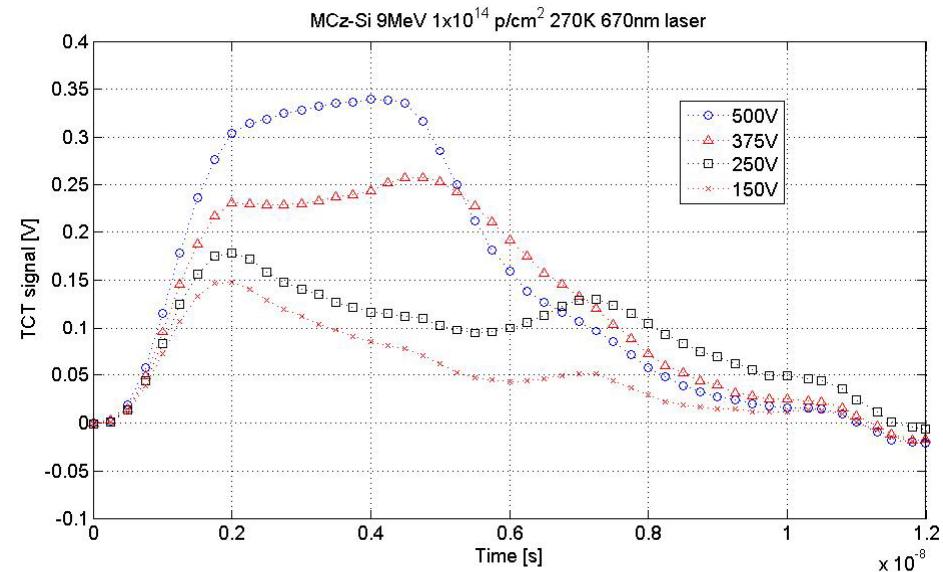


## TCT red laser results low energy protons 2

MCz-Si  $2.5 \times 10^{14}$  n<sub>eq</sub>/cm<sup>2</sup> by 9 MeV protons



MCz-Si  $5 \times 10^{14}$  n<sub>eq</sub>/cm<sup>2</sup> by 9 MeV protons



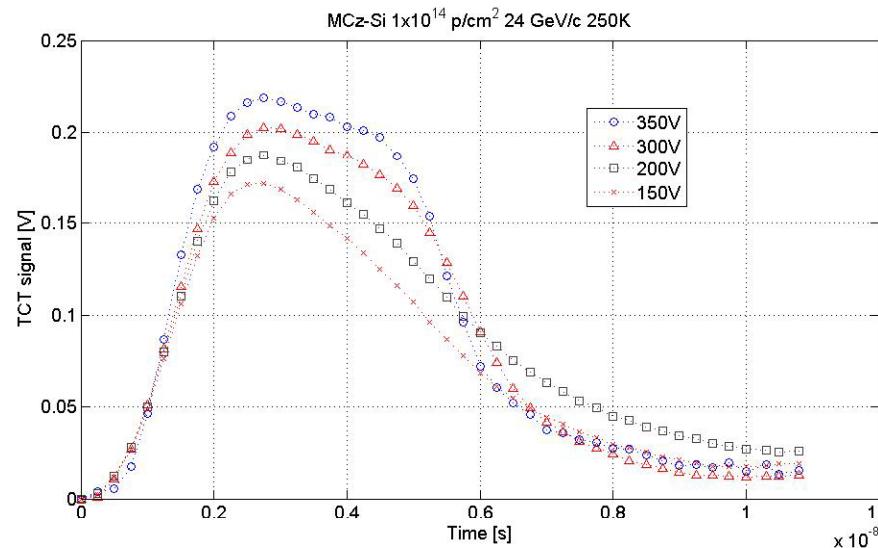
- No trapping correction
- Slight tendency for DP

- No trapping correction
- Increasing transient and DP

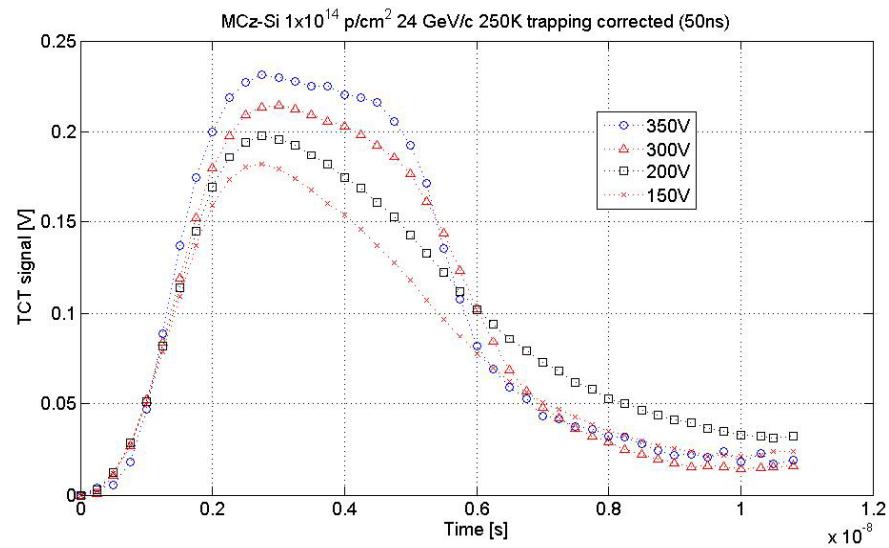


## TCT red laser results high energy protons 1

MCz-Si  $6 \times 10^{13}$  n<sub>eq</sub>/cm<sup>2</sup> by 24 GeV/c protons



MCz-Si  $6 \times 10^{13}$  n<sub>eq</sub>/cm<sup>2</sup> by 24 GeV/c protons



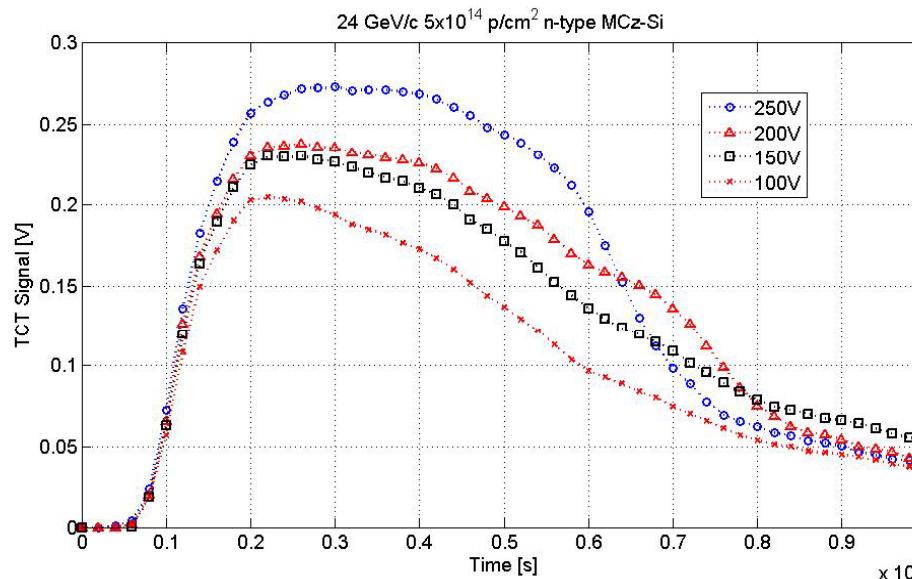
- No trapping correction

- Trapping corrected by 50ns
- $V_{fd} \approx 200V$
- Trapping effects negligible

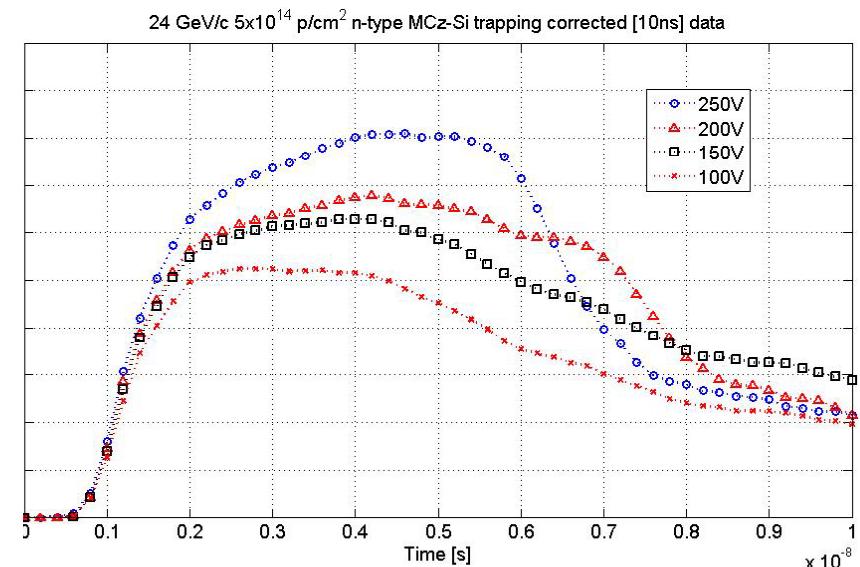


## TCT red laser results high energy protons 2

MCz-Si  $3 \times 10^{14}$  n<sub>eq</sub>/cm<sup>2</sup> by 24 GeV/c protons



MCz-Si  $3 \times 10^{14}$  n<sub>eq</sub>/cm<sup>2</sup> by 24 GeV/c protons



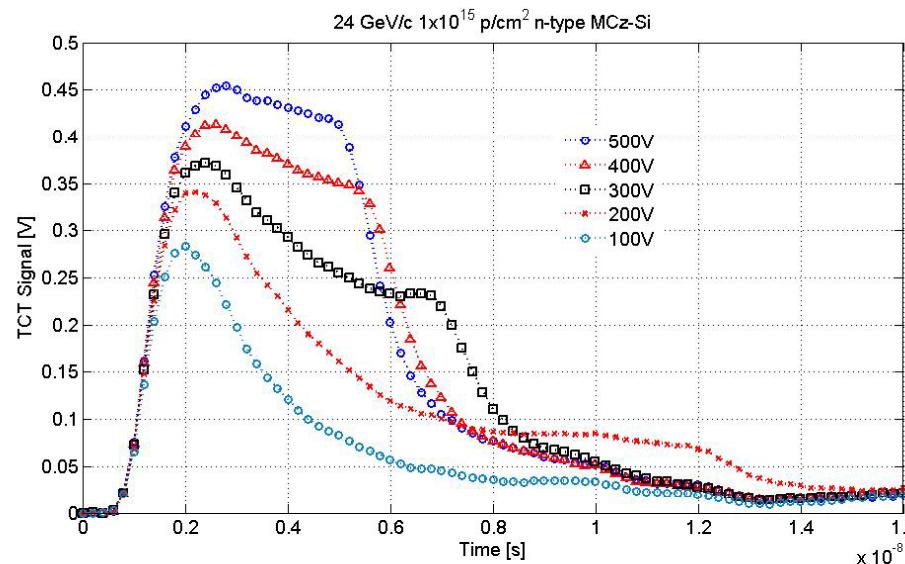
- No trapping correction
- DP arises in  $5 \times 10^{14}$  n<sub>eq</sub>/cm<sup>2</sup>

- Trapping corrected by 10ns
- $V_{fd} \approx 200V$

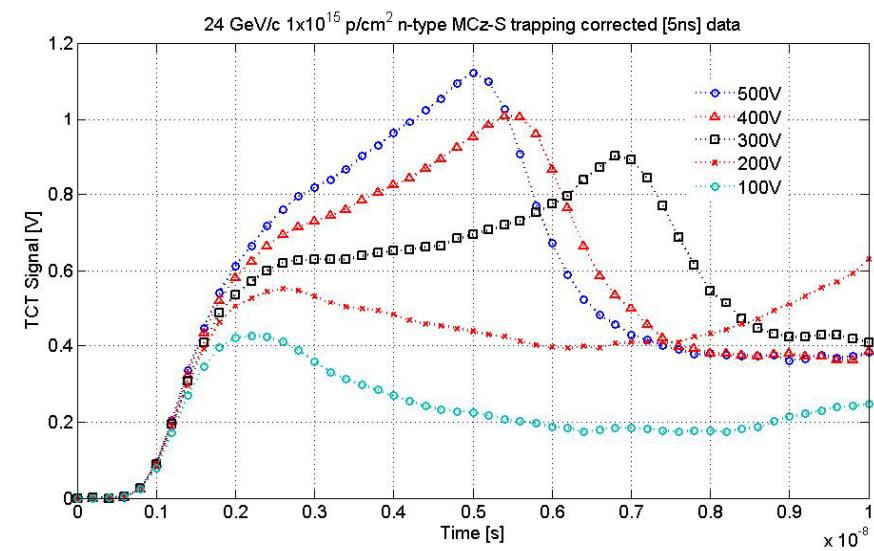


## TCT red laser results high energy protons 3

MCz-Si  $6 \times 10^{14}$  n<sub>eq</sub>/cm<sup>2</sup> by 24 GeV/c protons



MCz-Si  $6 \times 10^{14}$  n<sub>eq</sub>/cm<sup>2</sup> by 24 GeV/c protons

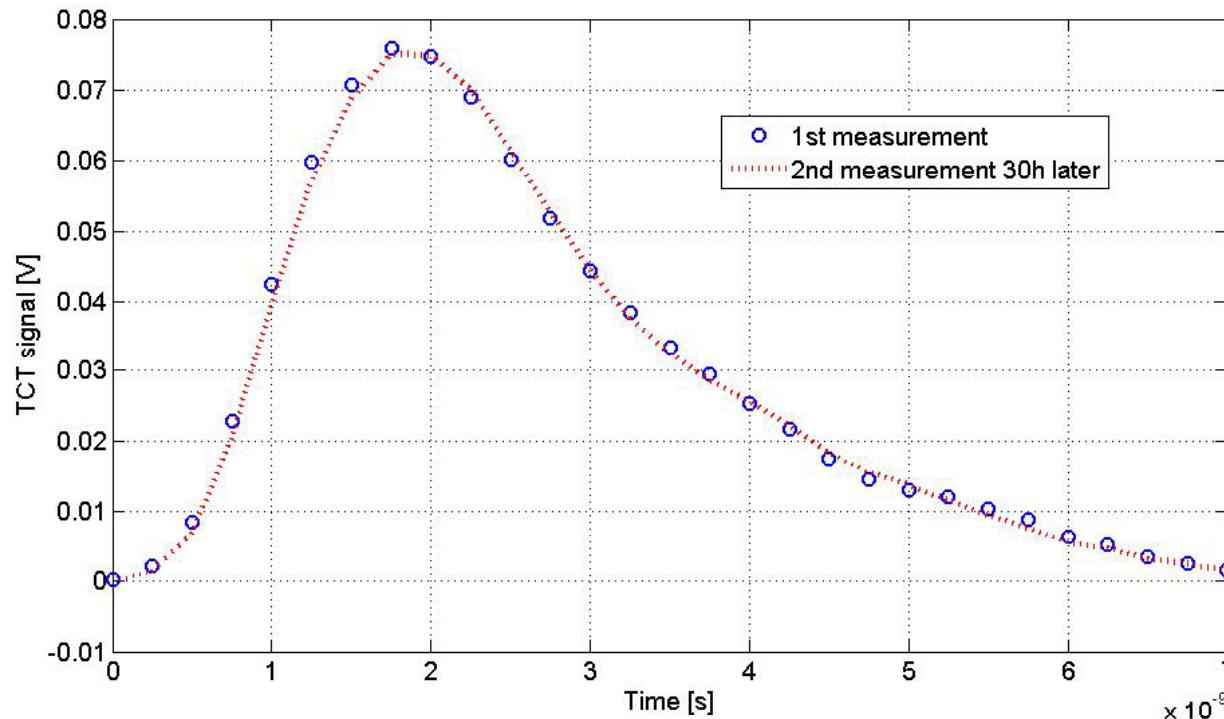


- No trapping correction

- Trapping corrected by 5ns



## CCE with infrared laser

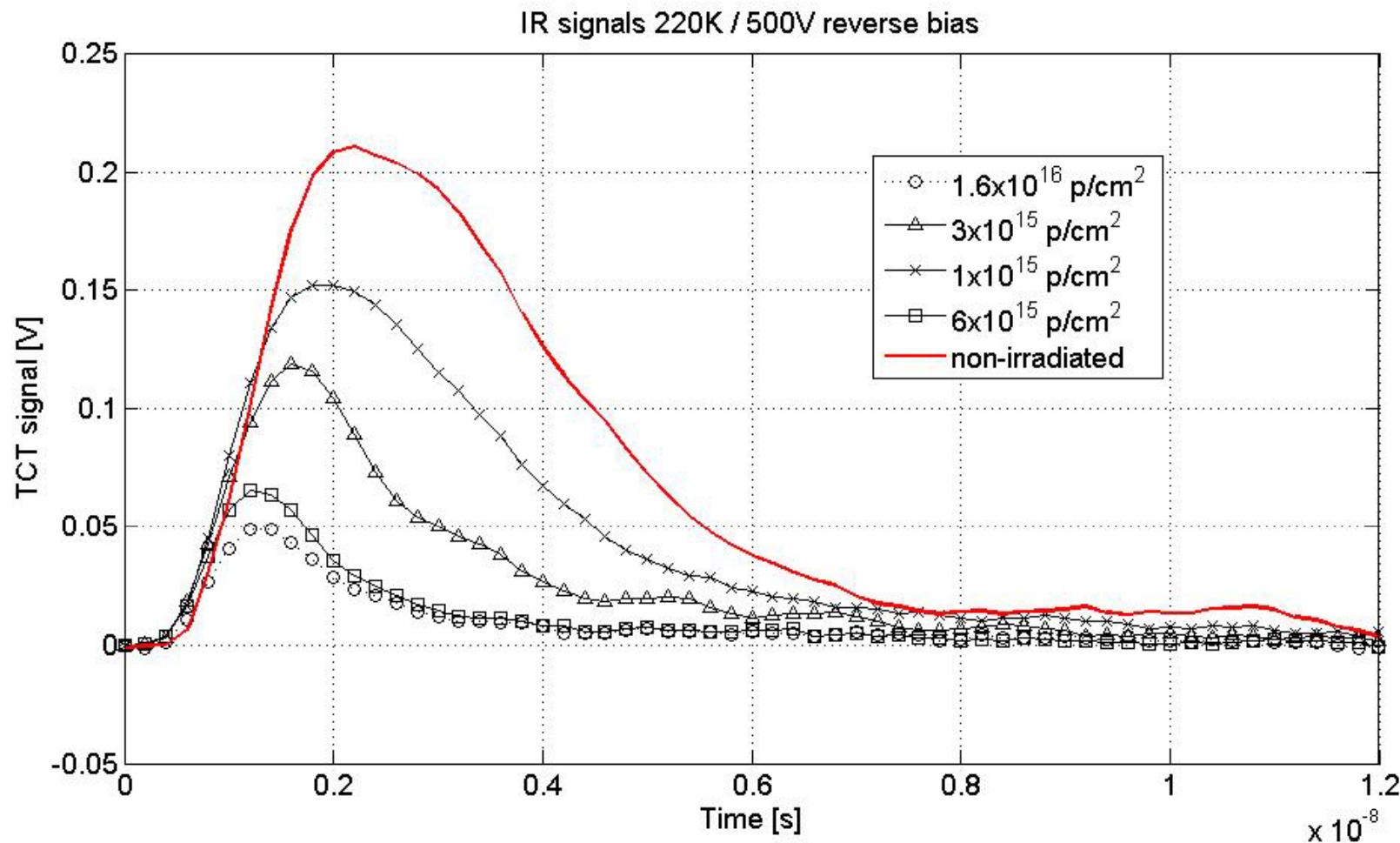


- Comparison of irradiated sample and non-irradiated reference
- Samples prepared *exactly* same manner
- High gain (~600) amplifier
- Injection level 10-20 MIPs

Stability of IR laser over ~30 hours

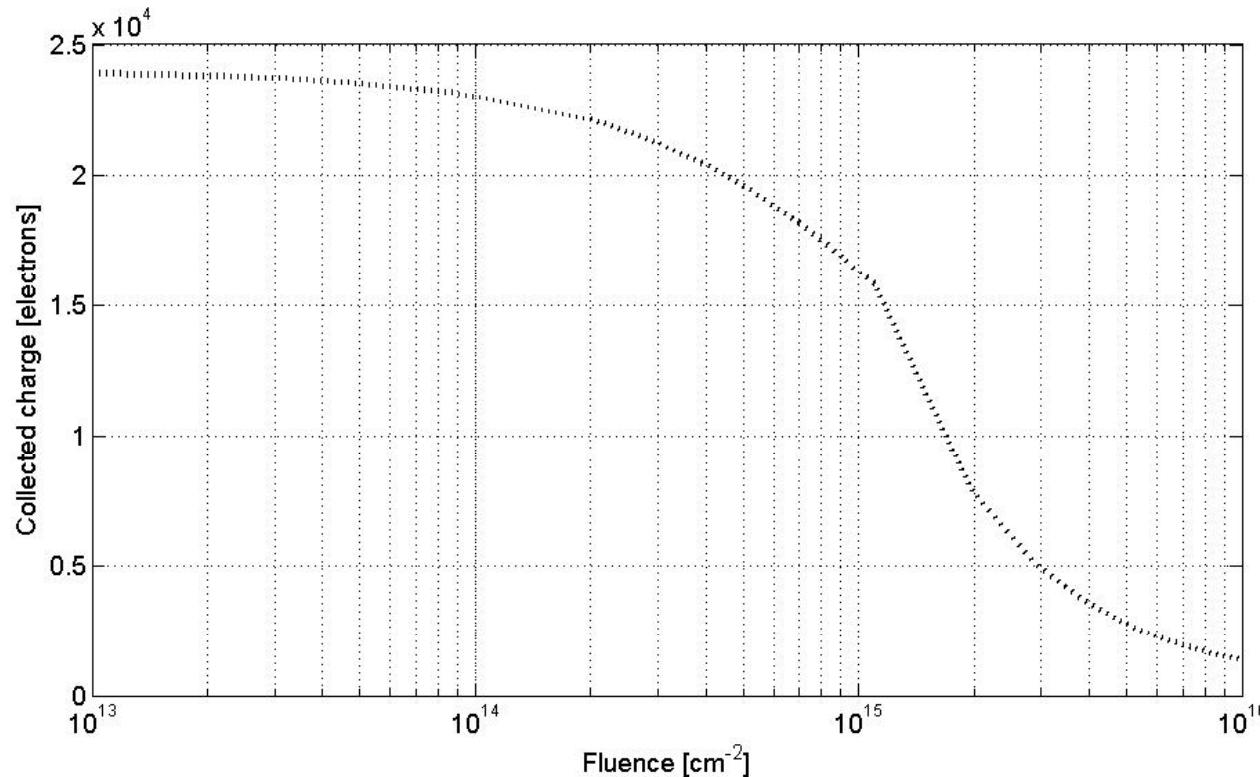


## IR transients of 24 GeV/c irradiated MCz-Si





## Expected Charge Collection Efficiency

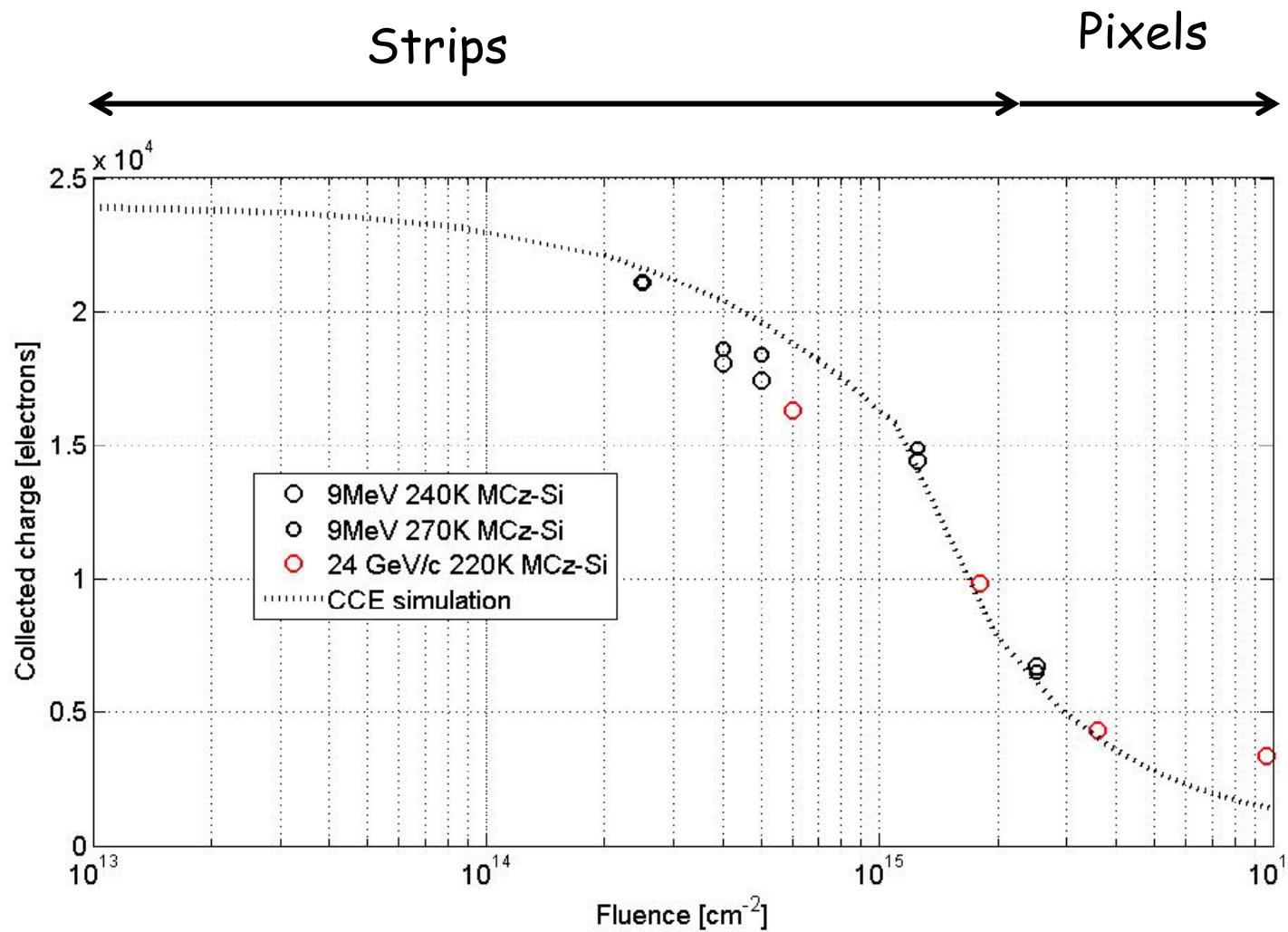


- Simulation takes into account linear trapping and evolution of  $V_{fd}$
- $\beta=0.01 \text{ cm}^{-1}$
- Linear E-field distribution is assumed

$$CCE = CCE_{\text{Geometrical}} \times CCE_{\text{trapping}} = \frac{w}{d} \times e^{-t_{dr}/\tau_{\text{trapping}}}$$



# Charge Collection Efficiency





## Summary

- MCz-Si shows different red laser response when irradiated by low energy and high energy protons.
- Low energy protons TCT transients reveal Double Junction and SCSI without trapping correction.
- High energy protons TCT transients reveal Double Junction and SCSI when trapping effects are taken into account.
- CCE at  $2 \times 10^{15} \text{ cm}^{-2}$  is about 30% / 8000e<sup>-</sup>. Thus, 300μm thick MCz-Si is feasible for strip layers but not for pixel barrel.
- The CCE is limited by trapping and elevated  $V_{fd}$ .
- Pad detector characterization does not include possible weighting field effects → systematic test beam experiments with segmented detectors and appropriate RO electronics are needed





## Acknowledgement

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- Staff of CERN Cryolab for technical assistance.